

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IPD25N06S4L-30	**Issued**	24. February 2022
MA#	MA005706135		
Package	PG-TO252-3-11	**Weight***	369.32 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.678	0.18	0.18	1837	1837
leadframe	inorganic material	phosphorus	7723-14-0	0.065	0.02		175	
	non noble metal	iron	7439-89-6	0.215	0.06		583	
	non noble metal	copper	7440-50-8	215.017	58.20	58.28	582195	582953
wire	non noble metal	aluminium	7429-90-5	0.987	0.27	0.27	2671	2671
encapsulation	inorganic material	zincoxide	1314-13-2	1.282	0.35		3472	
	miscellaneous	miscellaneous	-	6.411	1.74		17359	
	plastics	epoxy resin	-	19.233	5.21		52077	
	inorganic material	silicondioxide	60676-86-0	101.295	27.43	34.73	274274	347182
leadfinish	non noble metal	tin	7440-31-5	3.740	1.01	1.01	10127	10127
plating	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	nickel	7440-02-0	0.091	0.02	0.02	246	247
solder	non noble metal	tin	7440-31-5	0.022	0.01		60	
	noble metal	silver	7440-22-4	0.028	0.01		75	
	non noble metal	lead	7439-92-1	1.054	0.29	0.31	2854	2989
heatspreader	inorganic material	phosphorus	7723-14-0	0.006			16	
	non noble metal	iron	7439-89-6	0.019	0.01		52	
	non noble metal	copper	7440-50-8	19.177	5.19	5.20	51926	51994
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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